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APPLICATION NO.	1	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/901,581 07/09/2001		07/09/2001	Takahisa Doba	ICC-222 CIP	4798	
31217	7590	02/15/2006		EXAMINER		
LOCTITE CORPORATION				SELLERS, ROBERT E		
1001 TROUT BROOK CROSSING ROCKY HILL, CT 06067				ART UNIT	PAPER NUMBER	
,				1712		

DATE MAILED: 02/15/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)		
09/901,581	DOBA, TAKAHISA		
Examiner	Art Unit		
Robert Sellers	1712		

	Robert Sellers	1712	
The MAILING DATE of this communication appe	ars on the cover sheet with the	correspondence add	ress
THE REPLY FILED 03 February 2006 FAILS TO PLACE THIS		· · · · · · · · · · · · · · · · · · ·	
1. The reply was filed after a final rejection, but prior to or on this application, applicant must timely file one of the follow places the application in condition for allowance; (2) a No a Request for Continued Examination (RCE) in compliance time periods:	the same day as filing a Notice of ving replies: (1) an amendment, af tice of Appeal (with appeal fee) in	Appeal. To avoid aba fidavit, or other evider compliance with 37 C	nce, which FR 41.31; or (3)
 a)	dvisory Action, or (2) the date set forth		
Examiner Note: If box 1 is checked, check either box (a) or TWO MONTHS OF THE FINAL REJECTION. See MPEP 7	(b). ONLY CHECK BOX (b) WHEN TH		
Extensions of time may be obtained under 37 CFR 1.136(a). The date have been filed is the date for purposes of determining the period of ex under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the set forth in (b) above, if checked. Any reply received by the Office later may reduce any earned patent term adjustment. See 37 CFR 1.704(b) NOTICE OF APPEAL	on which the petition under 37 CFR 1. tension and the corresponding amount shortened statutory period for reply origon than three months after the mailing date.	of the fee. The appropri	iate extension fee ice action; or (2) as
 The Notice of Appeal was filed on A brief in comp filing the Notice of Appeal (37 CFR 41.37(a)), or any exte a Notice of Appeal has been filed, any reply must be filed AMENDMENTS 	nsion thereof (37 CFR 41.37(e)), to	avoid dismissal of th	ns of the date of e appeal. Since
 The proposed amendment(s) filed after a final rejection, They raise new issues that would require further co They raise the issue of new matter (see NOTE belo 	nsideration and/or search (see NO		ecause
(c) They are not deemed to place the application in bet appeal; and/or	ter form for appeal by materially re		the issues for
(d) ☐ They present additional claims without canceling a NOTE: (See 37 CFR 1.116 and 41.33(a)).	corresponding number of finally rej	ected claims.	
 4. The amendments are not in compliance with 37 CFR 1.13 5. Applicant's reply has overcome the following rejection(s) 		ompliant Amendment	(PTOL-324).
 Newly proposed or amended claim(s) would be all non-allowable claim(s). 		timely filed amendme	ent canceling the
7. For purposes of appeal, the proposed amendment(s): a) how the new or amended claims would be rejected is protected. The status of the claim(s) is (or will be) as follows: Claim(s) allowed: Claim(s) objected to: Claim(s) rejected: 1,3-7 and 10-19. Claim(s) withdrawn from consideration: 2,8 and 9.		II be entered and an e	explanation of
AFFIDAVIT OR OTHER EVIDENCE			
8. The affidavit or other evidence filed after a final action, bu because applicant failed to provide a showing of good and was not earlier presented. See 37 CFR 1.116(e).	t before or on the date of filing a N d sufficient reasons why the affidat	otice of Appeal will <u>no</u> vit or other evidence is	<u>it</u> be entered s necessary and
 The affidavit or other evidence filed after the date of filing entered because the affidavit or other evidence failed to of showing a good and sufficient reasons why it is necessary 	vercome <u>all</u> rejections under appe y and was not earlier presented. S	al and/or appellant fai see 37 CFR 41.33(d)(ils to provide a 1).
 The affidavit or other evidence is entered. An explanatio <u>REQUEST FOR RECONSIDERATION/OTHER</u> 		•	
 The request for reconsideration has been considered bu <u>See the attachment.</u> 	,		nce because:
12. Note the attached Information Disclosure Statement(s).	PTO/SB/08 or PTO-1449) Paper N	lo(s)	
13. ☑ Other: Form PTO-892, Notice of References Cited.			
		Robert Sellers	

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1. The amendment after Final rejection filed February 3, 2006 has been denied entry because independent claim 1 limited to a reaction product of the thermosetting resin composition raises new issues with respect to the capability of the prior art cured compositions to soften and lose its adhesiveness upon exposure to temperatures in excess of the curing temperature. Independent claim 15 remains denoted as an unreacted thermosetting resin composition.

- 2. The amendment to the specification, page 14, line 4 wherein Ancamine 2337 is more accurately described as a modified novolac epoxy resin has not been made since the amendment after Final rejection filed December 14, 2005 has been denied entry as set forth in the advisory action mailed December 22, 2005.
- 3. The last four lines of claim 1 requires the proviso "wherein when exposed to temperature conditions in excess of those used to cure the composition, the reaction product softens and lose its adhesiveness so as to permit easy separation of substrates bonded together therewith." The specification on page 21, lines 24-32 describes the procedure:

"By heating the area around the semiconductor device which has failed is heated at a temperature of about 190°C to about 260°C for a period of time ranging from about 10 seconds to about 1 minute . . .

As soon as the solder is melted and the resin is softened to cause a reduction in bond strength, the semiconductor device is pulled apart."

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4. The specification does not support the exposure of the reaction product to a temperature generally in excess of the cure temperature. Only a specific range of from about 190°C to about 260°C is disclosed for a certain period of from about 10 seconds to about 1 minute. The reduction in bond strength does not substantiate the claimed loss in bond strength since a mere reduction embraces the retention of a certain minimal level of bond strength. The claimed "easy separation" of the bonded substrates is not supported by the disclosed semiconductor device being "pulled apart."

It cannot be ascertained what degree of strength is required to satisfy the word "easy."

- 5. The Information Disclosure Statement filed February 3, 2006 contains initialed copies of previously considered Forms PTO-1449 along with copies of the documents. PCT Publication No. WO 99/05196 has been previously cited in the Form PTO-892, Notice of References Cited mailed June 30, 2005. The attached Form PTO-892 acknowledges the consideration of the previously unconsidered references on the Forms PTO-1449. However, the Korean Patent No. 1998-42952 and the technical bulletins for KS M 0009 and Doosan World Encyclopedia are presented in Korean and cannot be reviewed until English translations are submitted. Tsukada Patent No. 5,355,580 is an equivalent of Japanese Patent No. 5-251516.
- 6. The arguments filed February 3, 2006 are a reiteration of those presented with the amendment after Final rejection filed December 14, 2005 and have been addressed in the advisory action mailed December 22, 2005.

(571) 272-1093 (Fax No. (571) 273-8300) Monday to Friday, 9:30 to 6:00

rs 2/8/2006

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PRIMARY EXAMINER